

**Amendments to the Claims are as follows:**

1. (Currently Amended) An electronic unit comprising:

a module in which a semiconductor device is attached on ~~at~~the bottom of a circuit board and which has lands provided on the bottom of the circuit board with the lands being connected to the semiconductor device; and

a printed circuit board on which the module is mounted,

the printed circuit board having a hole in a position facing the semiconductor device and having electrical conductors to which the lands are soldered,

wherein the module is mounted on the printed circuit board by soldering the lands to the electrical conductors while the semiconductor device is disposed in the hole.

2. (Original) An electronic unit according to Claim 1, wherein solder balls are applied on the lands, and the lands and the electric conductors are soldered together with the solder balls.

3. (Currently Amended) An electronic unit according to Claim 2, wherein ~~at~~the wall of the hole has recesses that receive the corresponding solder balls and have electrical conductors applied to ~~the~~ walls of the recesses.